

(1.27 mm) .050"

# HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAF](http://www.samtec.com?SEAF)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Operating Temp Range:**

-55 °C to +125 °C

**Current Rating**

(7 mm stack height):  
2.7 A per pin  
(10 adjacent pins powered)

**Plating:**

Au or Sn over

50 µ" (1.27 µm) Ni

**Working Voltage:**

240 VAC

**RoHS Compliant:**

Yes

**Lead-Free Solderable:**

Yes

**Board Mates:**

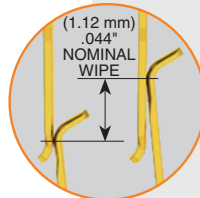
SEAM, SEAMP,  
SEAR, SEAMI

**Cable Mates:**

SEAC

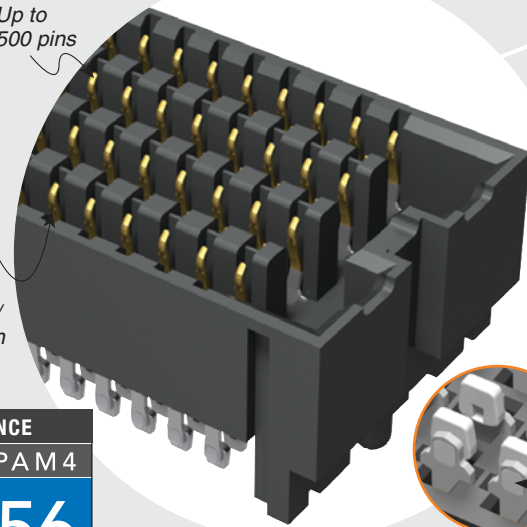
**Standoffs:**

JSO



Up to 500 pins

Low insertion/  
extraction forces



Solder charges

## HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

PAM 4

56 Gbps

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

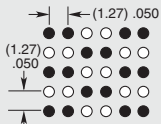


## STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

Visit [www.samtec.com/standards](http://www.samtec.com/standards) for more information.

## DIFFERENTIAL SIGNAL ROUTING



The above signal routing configuration allows for the use of 25 to 125 differential pair counts. Contact [sig@samtec.com](mailto:sig@samtec.com) for specific details.

**Notes:**  
Patented

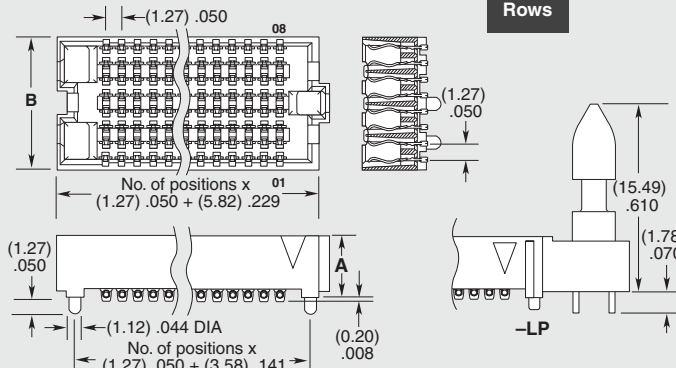
IPC-A-610F and IPC J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.

SEAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION	K	TR
	-10, -15, -20, -30, -40, -50	Specify LEAD STYLE from chart	-L = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail -S = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -05 = Five Rows -06 = Six Rows -08 = Eight Rows -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge		-LP = Latch Post (-LP required for SEAC mate only) (Available with -05.0 lead style and -04, -06, -08 & -10 rows only)	-K = Polyimide film Pick & Place Pad (Not available with -10 and -15 pins with -LP Latch post)	

NO. OF ROWS	B
-04	(5.66) .223
-05, -06	(8.20) .323
-08	(10.74) .423
-10	(13.28) .523

LEAD STYLE	A
-05.0	(5.05) .199
-06.0	(6.05) .238
-06.5	(6.55) .258
-07.5	(7.54) .297

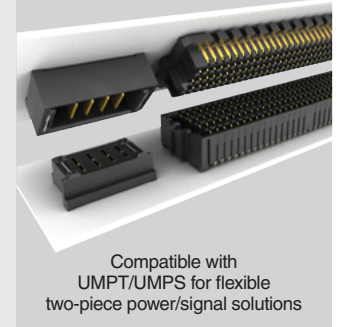


Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.

## POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions